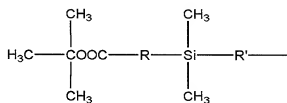


Abstract

This invention relates to photosensitive silicone resins and resin compositions containing the same. Silicone resins of this invention are characterized by that a triorganosilyl group represented by the following general formula (1)



(1)

(wherein R is a divalent organic group and R' is a divalent group or a direct bond) is linked to all or a part of the ends of the backbone of polyorganosilsesquioxanes. Photosensitive resin compositions of this invention are formulated from the aforementioned silicone resins and a photogenerator of acid.

The aforementioned silicone resins and photosensitive resin compositions show excellent performance as resist materials for multi-level resist processes and for forming barriers of PDP and, on account of their excellent plasma resistance (resistance to O₂-RIE), yield patterns of a high aspect ratio.